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## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO.

: 6,821,821 B2

DATED: November 23, 2004

INVENTOR(S) : Joseph Fjelstad

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 3,

Lines 35-37, "chip package having a second semiconductor chip back-bonded to the first chip such separate" should read -- chip package having a separate --.

Signed and Sealed this

Tenth Day of May, 2005

JON W. DUDAS
Director of the United States Patent and Trademark Office